

REMARKS/ARGUMENTS

The foregoing amendment and the following arguments are provided to impart precision to the claims, by more particularly pointing out the invention, rather than to avoid prior art.

35 U.S.C. § 102(b) Rejections

Examiner rejected claims 16, 17, 19, 20, 24, 25, 29, 30, 34, 35, 38 and 39 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent 5,473,199 (hereinafter "Murakami").

To anticipate a claims, the reference must teach every element of the claim. A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference. (Manual of Patent Examining Procedures (MPEP) ¶ 2131.)

Applicant's independent claims 16, 24, and 34 include limitations not disclosed nor suggested by Murakami. As a result, Murakami does not anticipate applicant's independent claims 16, 24, and 34.

In particular, applicant's independent claims include the limitation, or a limitation similar thereto, of a mold cap disposed over the substrate such that the mold cap at least partiality covers the chip, the mold cap having a plurality of extensions each extending into a respective corner section of the substrate, *the extensions extend into the corner sections of the substrate without extending to edges of the substrate.*

Murakami does not disclose nor suggest the claimed limitation of a mold cap disposed over the substrate such that the mold cap at least partiality covers the chip, the mold cap having a plurality of extensions each extending into a respective corner section of the substrate, *the extensions extend into the corner sections of the substrate without extending to edges of the substrate.*

Rather, Murakami discloses a cover that covers all corners of the substrate. As stated in the summary of Murakami:

Another and more specific object of the present invention is to provide a semiconductor device comprising a semiconductor device body including a resin package and a plurality of leads extending outwardly from the resin package, *a ring part made of a resin and surrounding the semiconductor device body*, and a plurality of connecting parts made of a resin and connecting the semiconductor device body and the ring part, *so that the semiconductor device body is supported by the ring part via the connecting parts.* (Murakami Summary, col. 2, lines 25-33).

As a result of Murakami failing to disclose or suggest applicant's claimed limitations, Murakami does not anticipate applicant's independent claims 16, 24, and 34.

In addition, the remaining claims depend from one of independent claims 16, 24, and 34, and therefore include the distinguishing claim limitations of claims 16, 24, and 34, as discussed above. As a result, the remaining claims are also not anticipated by Murakami.

CONCLUSION

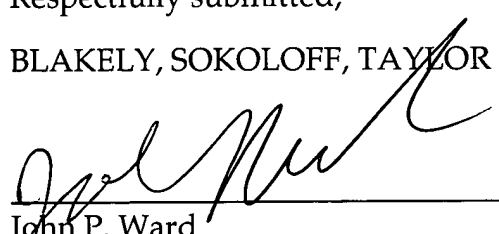
Applicant respectfully submits the present application is in condition for allowance. If the Examiner believes a telephone conference would expedite or assist in the allowance of the present application, the Examiner is invited to call John Ward at (408) 720-8300, x237.

Authorization is hereby given to charge our Deposit Account No. 02-2666 for any charges that may be due.

Respectfully submitted,

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